

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03092	10.0	0.61206
	Silver alloy	Silver (Ag)	7440-22-4	0.00618	2.0	0.12241
	Lead alloy	Lead (Pb)	7439-92-1	0.27209	88.0	5.38615
			Subtotal	0.30919	100	6.12062
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.1783	7.7	43.12
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.39475	12.0	67.2
	Filler	Silica fused	60676-86-0	22.63166	80.0	448
	Carbon Black	Carbon black	1333-86-4	0.08487	0.3	1.68
			Subtotal	28.28958	100	560
Lead Frame	Iron-nickel alloy	Phosphorous (P)	7723-14-0	0.02085	0.03	0.4128
	Iron-nickel alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.75072	1.08	14.8608
	Iron-nickel alloy	Copper (Cu)	7440-50-8	68.67044	98.79	1,359.3504
			Subtotal	69.44201	99.9	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.04469	100.0	20.68
			Subtotal	1.04469	100	20.68
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.43257	100.0	8.56275
			Subtotal	0.43257	100	8.56275
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.41243	100.0	8.16423
			Subtotal	0.41243	100	8.16423
Total				99.93047	100	NaN

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